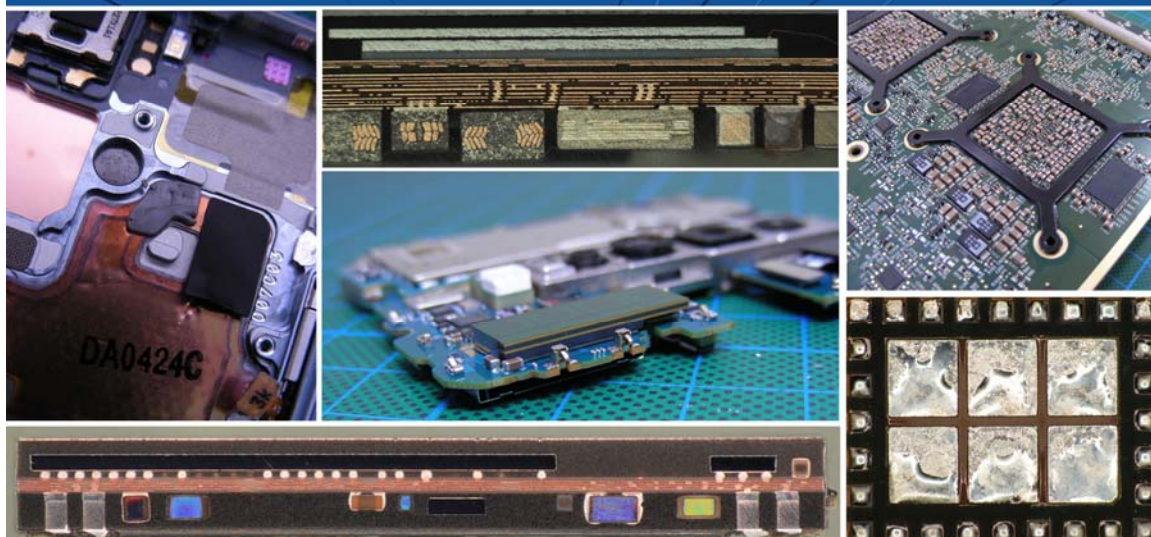


# THE SEMICONDUCTOR AND PACKAGING REPORT

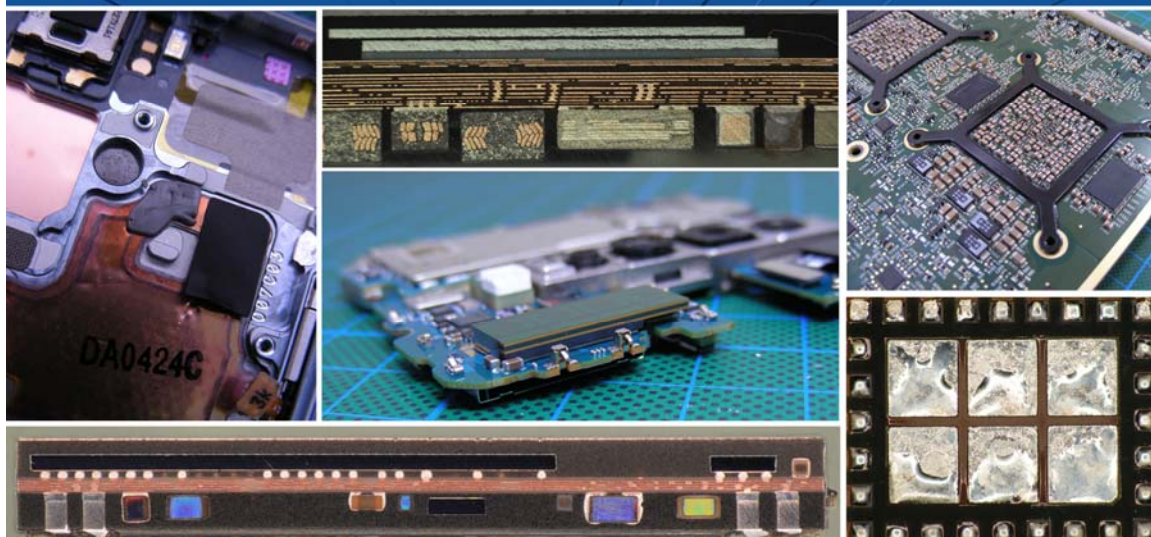
SECOND QUARTER • SEPTEMBER 2020



- State of the Semiconductor and Package Business
  - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2020 and 2021, including COVID-19 impact; actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- Advanced Packaging for High-Performance Applications
  - Updated review of high-performance packages including advanced FCCSP, FCBGA, FO-MCM, 2.5D, bridge chip approaches, and 3D packaging developments. Includes details of notable products released in 2020, including the latest Intel Lakefield Processor using 3D-TSV interconnect.
- China's CPU and AI Chip Suppliers
  - Summary of leading IC design houses in China looking to support demand for local and global electronics systems requiring advanced CPU and AI processors.
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings.
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations.

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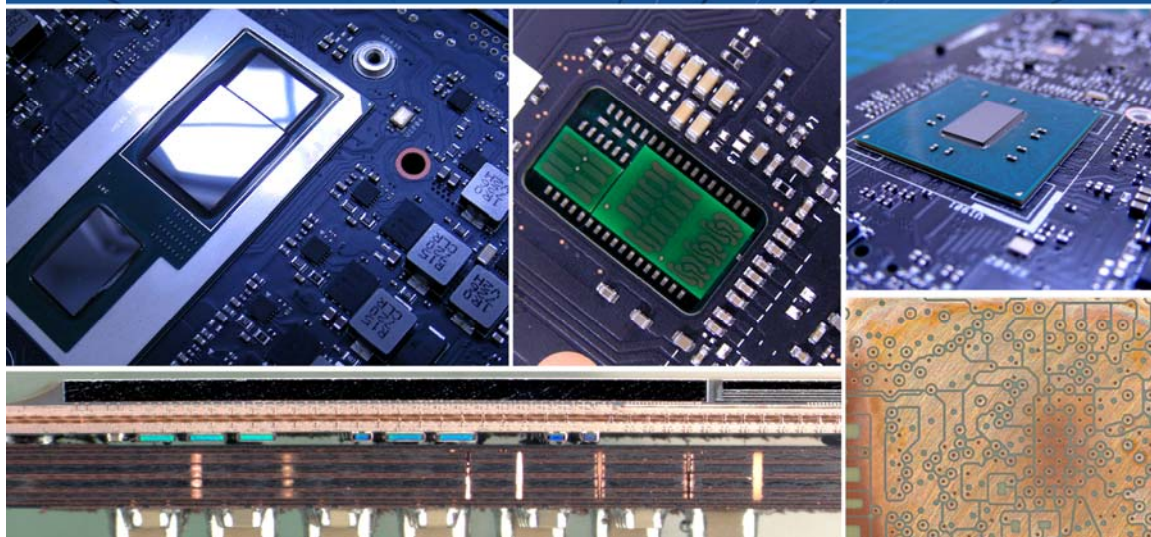
FIRST QUARTER • JUNE 2020



- State of the Semiconductor and Package Business
  - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2020, including COVID-19 impact; actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- Wafer-Level CSP (WLCSP)
  - Overview of fan-in and fan-out WLCSP market including market size players and product teardowns. Includes a market update outlook for simple, complex and FO-MCM devices and value out to 2024.
- Updates on China's Handset Market and the ODMs
  - An updated review of the leading china based EMS/ODM players serving the mobile phone market including current outlooks.
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings.
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations.

# THE SEMICONDUCTOR AND PACKAGING REPORT

FOURTH QUARTER • MARCH 2020

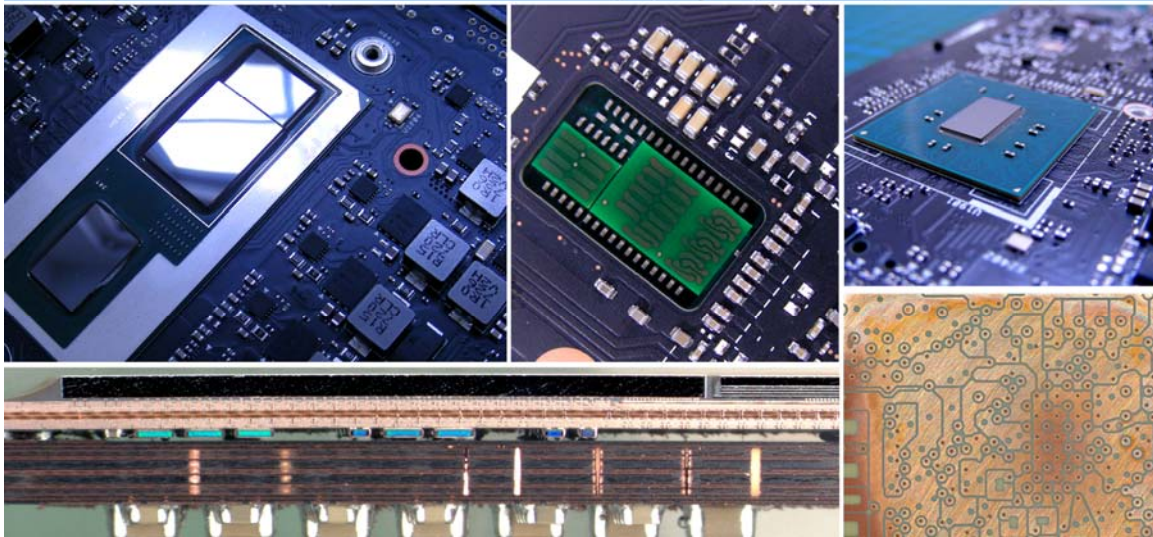


- State of the Semiconductor and Package Business
  - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2020, including COVID-19 impact; actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- Semiconductor and Packaging: Five-Year Outlook
  - A forecast for all device shipments to 2024 based on future systems demand, current trends, and projected silicon integration.
- IC Packaging Forecast Overview
  - Review of the overall server market with a focus on Chinese- and Taiwanese-based OEMs and ODMs.
- Recent Teardowns
  - Teardowns of Intel Xeon Server CPU, Broadcom Front-end Module, and Apple Air Pod SiP.
- Updates on Taiwanese ODMs
  - An updated review of Taiwan-based EMS/ODM players including current outlooks.



# THE SEMICONDUCTOR AND PACKAGING REPORT

THIRD QUARTER • DECEMBER 2019



- State of the Semiconductor and Package Business
  - Review of the status of semiconductor shipments; Prismark's global economic and electronics forecast for 2020; actual and forecast sales of OEM, EMS, semiconductor suppliers, package assemblers, and foundries.
- Package Substrates: Focus on FCCSP and FCBGA
  - Highlights of fast growing package substrate market, with a focus on FCCSP and FCBGA substrates. Includes examples of large size FCBGA/LGA that have been driving much of the market value growth in past year.
- Server Market Updates: Focus on China/Taiwan
  - Review of the overall server market with a focus on Chinese- and Taiwanese-based OEMs and ODMs.
- Company News: Semiconductor and Wafer Fabrication
  - News in the semiconductor and foundry businesses regarding leading players and new product offerings.
- Company News: Semiconductor Packaging
  - Recent developments in packaging at leading OSAT and captive assembly operations.



*CONSULTANTS TO THE ELECTRONICS INDUSTRY  
BUSINESS OPPORTUNITY FROM TECHNOLOGY AND  
MARKET CHANGES*

**PRISMARK PARTNERS LLC**

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